

MAIN CHARACTERISTICS

I_D	25A
V_{DSS}	500V
$R_{DS(on)-typ}$ (@ $V_{GS}=10V$)	0.205 Ω

FEATURES

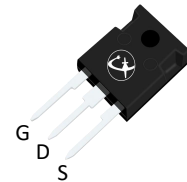
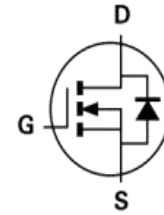
- Fast Switching
- Low ON Resistance
- Low Gate Charge
- 100% Single Pulse avalanche energy Test

APPLICATIONS

- Power switch circuit of adaptor and charger.

MECHANICAL DATA

- Case: Molded plastic
- Mounting Position: Any
- Molded Plastic: UL Flammability Classification Rating 94V-0
- Lead free in compliance with EU RoHS 2011/65/EU directive
- Solder bath temperature 275°C maximum, 10s per JESD 22-B106



TO-247S

Product specification classification

Part Number	Package	Mode Name	Pack
CS25N50A7	TO-247S	CS25N50A	Tube

Maximum Ratings at Tc=25°C unless otherwise specified

Characteristics	Symbol	Value	Unit
		247S	
Drain-Source Voltage	V_{DS}	500	V
Gate-Source Voltage	V_{GS}	± 30	V
Continue Drain Current	I_D	25	A
Pulsed Drain Current (Note1)	I_{DM}	100	A
Power Dissipation	P_D	300	W
Single Pulse Avalanche Energy (Note1)	E_{AS}	1500	mJ
Operating Temperature Range	T_J	150	°C
Storage Temperature Range	T_{STG}	-55 to +150	°C
Thermal Resistance, Junction to Case	$R_{\theta JC}$	0.42	°C/W
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	40	°C/W

Note1:Pulse test: 300 μ s pulse width, 2 % duty cycle

Electrical Characteristics at Tc=25°C unless otherwise specified

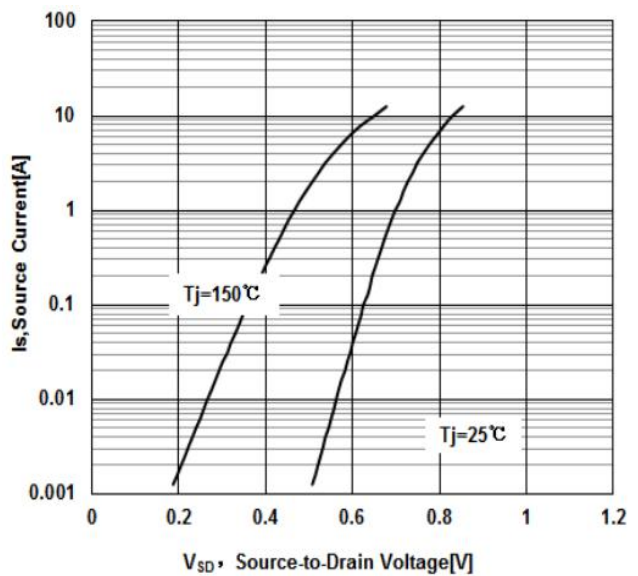
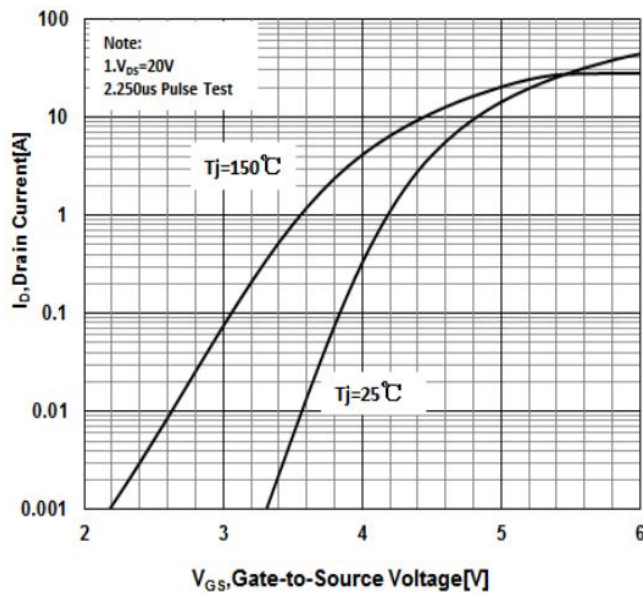
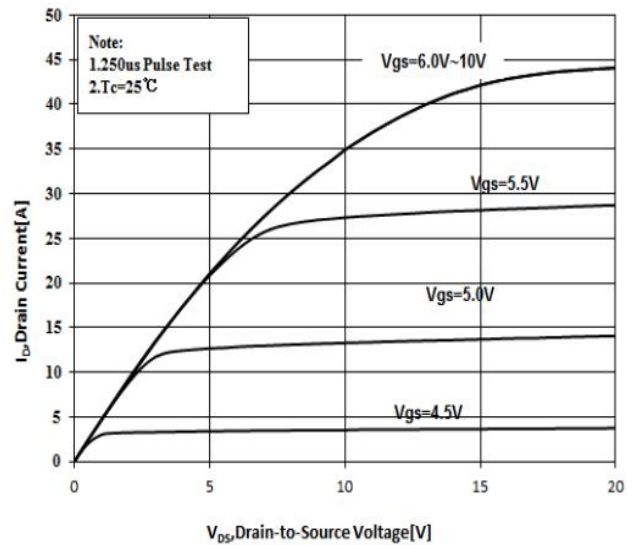
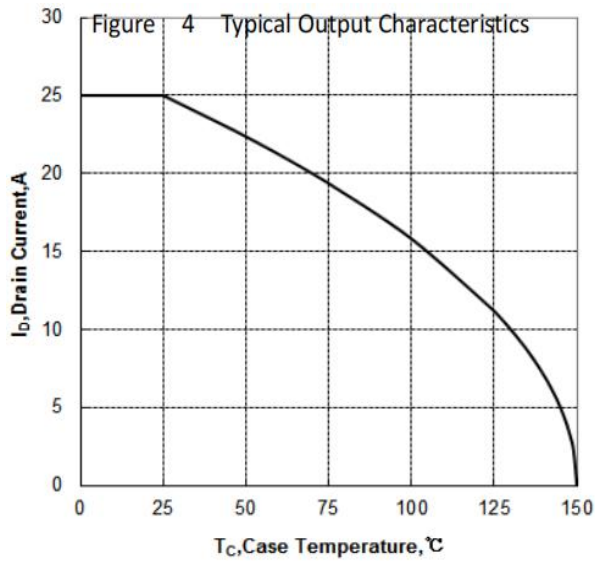
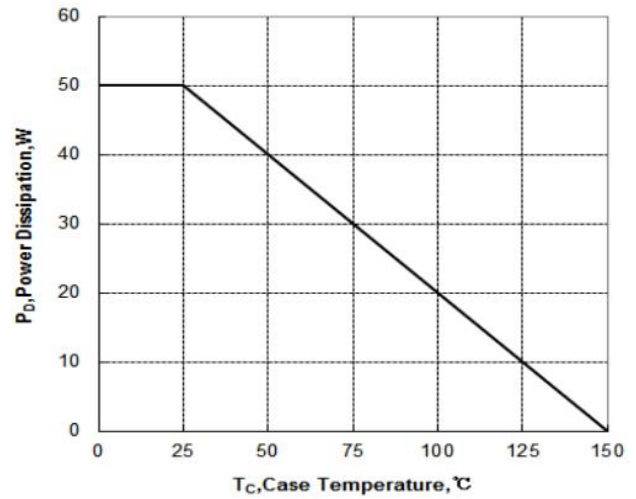
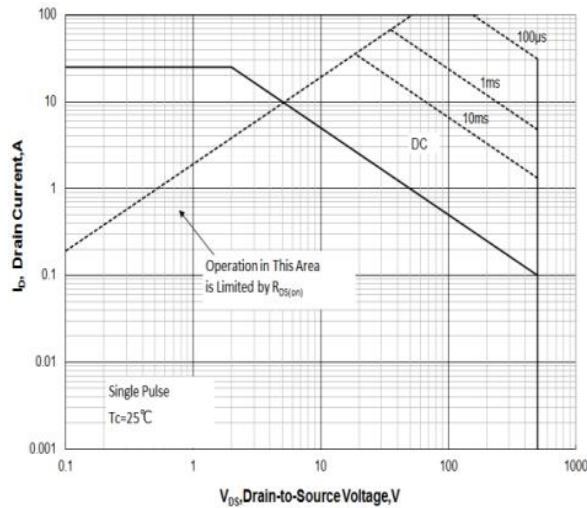
Characteristics	Test Condition	Symbol	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	BV_{DSS}	500	-	-	V
Drain-Source Leakage Current	$V_{DS} = 500 \text{ V}, V_{GS} = 0 \text{ V}$	I_{DSS}	-	-	1	μA
Gate Leakage Current	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	I_{GSS}	-	-	± 100	nA
Gate-Source Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	$V_{GS(th)}$	2	-	4	V
Drain-Source On-State Resistance	$V_{GS} = 10 \text{ V}, I_D = 12.5 \text{ A}$	$R_{DS(on)}$	-	0.205	0.26	Ω
Forward Transconductance	$V_{DS} = 15 \text{ V}, I_D = 12.5 \text{ A}$	g_{fs}	-	18	-	S
Input Capacitance	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1.0 \text{ MHz}$	C_{iss}	-	4700	-	pF
Output Capacitance		C_{oss}	-	210	-	pF
Reverse Transfer Capacitance		C_{rss}	-	10.4	-	pF
Turn-on Delay Time(Note2)	$I_D = 25 \text{ A}, V_{DD} = 250 \text{ V}, R_G = 10 \Omega$	$t_d(ON)$	-	37	-	ns
Rise Time(Note2)		t_r	-	64.8	-	ns
Turn-Off Delay Time(Note2)		$t_d(OFF)$	-	85.9	-	ns
Fall Time(Note2)		t_f	-	46.2	-	ns
Total Gate Charge(Note2)	$I_D = 25 \text{ A}, V_{DD} = 400 \text{ V}, V_{GS} = 10 \text{ V}$	Q_G	-	64.3	-	nC
Gate to Source Charge(Note2)		Q_{GS}	-	16.7	-	nC
Gate to Drain Charge(Note2)		Q_{GD}	-	23	-	nC

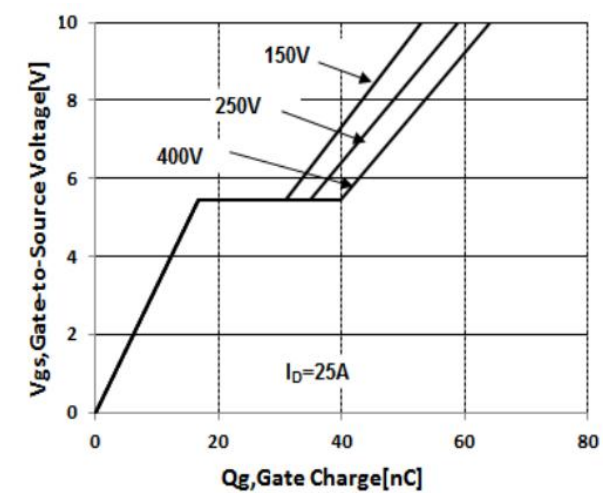
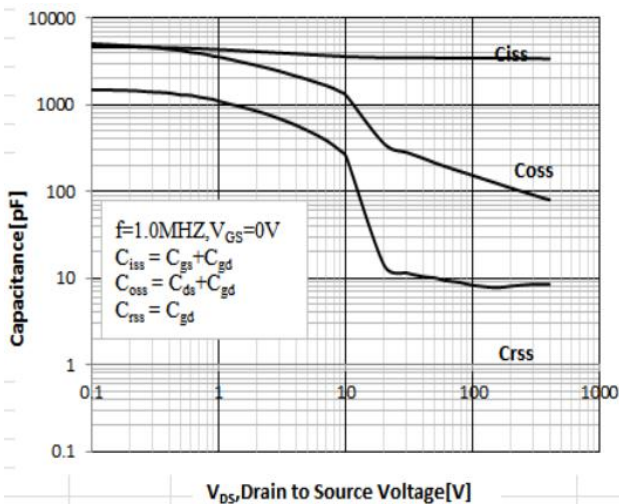
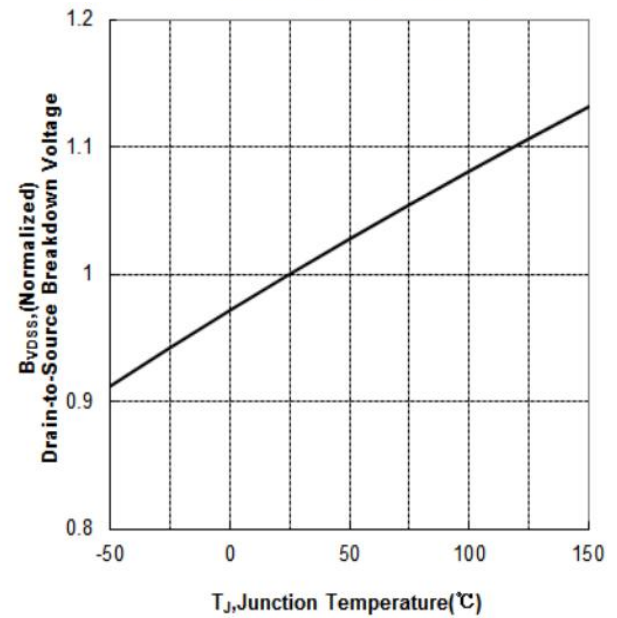
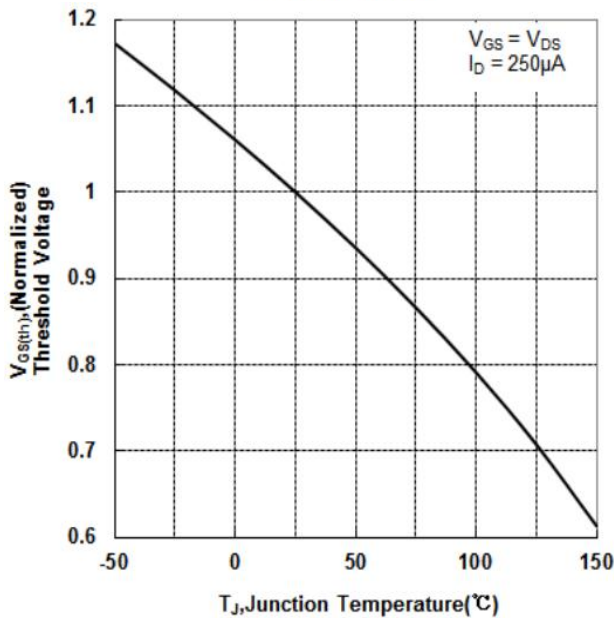
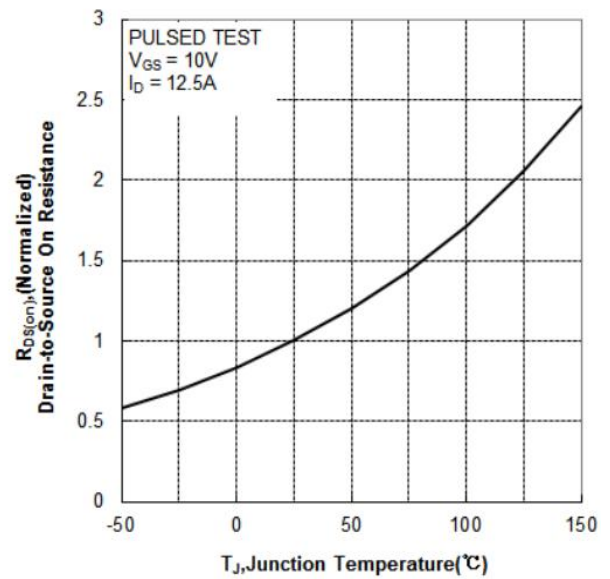
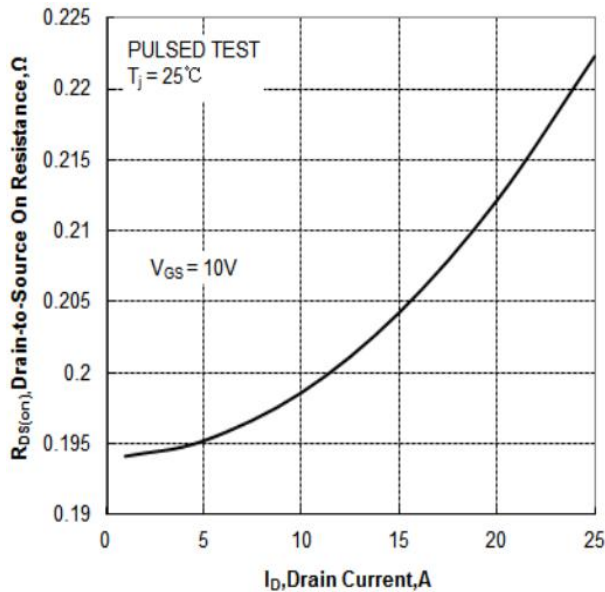
Source-Drain Diode Characteristics at Ta=25°C unless otherwise specified

Characteristics	Test Condition	Symbol	Min.	Typ.	Max.	Unit
Maximun Body-Diode Continuous Current		I_S	-	-	25	A
Maximun Body-Diode Pulsed Current(Note2)		I_{SM}	-	-	100	A
Drain-Source Diode Forward Voltage	$I_{SD} = 25 \text{ A}$	V_{SD}	-	-	1.5	V
Reverse Recovery Time(Note2)	$I_{SD} = 25 \text{ A}, V_{GS} = 0 \text{ V},$	t_{rr}	-	487	-	ns
Reverse Recovery Charge(Note2)	$dI_F / dt = 100 \text{ A}/\mu\text{s}$	Q_{rr}	-	6235	-	nC

Note2:Pulse test: 300 μ s pulse width, 2 % duty cycle

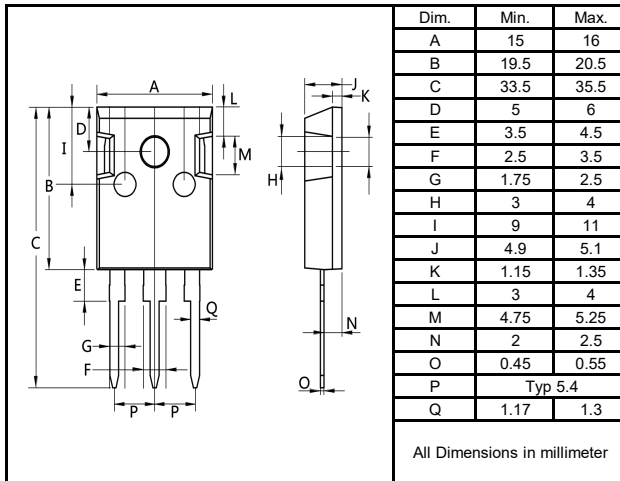
RATINGS AND CHARACTERISTIC CURVES



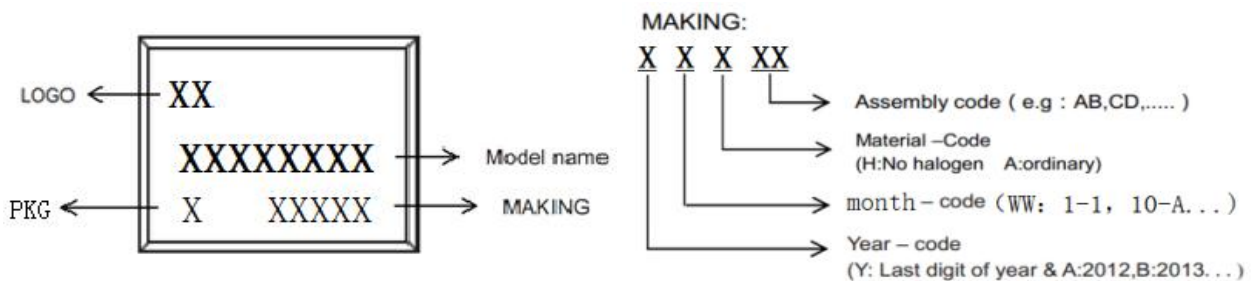


Package Outline Dimensions millimeters

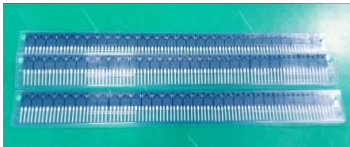
TO-247S



Marking on the body



packing instruction

PKG	Minimal Package	Mini Box	Box
TO-247S			
	30pcs/pdpe	600pcs/box	3000pcs/box



CS25N50A

N-Channel Enhancement Mode Power MOSFET

Notice

All product, product specifications and data are subject to change without notice to improve. The right to explain is owned by LINGXUN electronics company.

Confirm that operation temperature is within the specified range described in the product specification. Avoid applying power exceeding normal rated

power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.

LINGXUN electronics shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

<http://www.lxmicro.com>

Revision History

Rev	Changes	Date
1.0	First version	2025-9-2